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Amendments to the Claims

A detailed list of all claims under examination is set out below. Please add new claims 61-66 as shown below:

1-37. (Cancelled)

- 38. (previously presented): The article of claim 43 wherein the adhesive comprises a hot melt adhesive, pressure sensitive adhesive, curable adhesive, or filled adhesive.
- 39. (previously presented): The article of claim 38 wherein the adhesive comprises a filled electrically conductive adhesive, thermally conductive adhesive, or desiccating adhesive.
- 40. (previously presented): The article of claim 43 wherein there is a gap between the multi-layer structure and the surrounding adhesive.
- 41. (previously presented): The article of claim 43 wherein the article is an organic light emitting diode.
- 42. (previously presented): The article of claim 44 wherein the substrate comprises glass, the anode comprises indium tin oxide, the hole transporting layer comprises 4,4'-bis(naphthalen-2-yl)-N,N'-diphenyl benzidine, the light emitting layer comprises coumarin-doped tris(8-hydroxyquinolinato)aluminum, the electron transporting layer comprises bis(10-hydroxy-benzo(h)quinolinato) beryllium, bis(2-(2-hydroxy-phenyl)-benzolthiazolato) zinc, 3,4,5-triphenyl-1,2,4-triazole, or 2-(4-biphenylyl)-5-(4-t-butylphenyl)-1,3,4-oxadiazole, and the cathode comprises lithium fluoride and aluminum.

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- 43. (previously presented): An article comprising an organic electronic device which comprises:
 - a. a substrate;
 - b. an adhesive;
 - c. a multi-layer structure comprising one or more organic layers between an anode and a cathode, the anode, cathode or an organic layer having at least one outer edge; and
- d. a sealing layer,
 wherein the adhesive seals an outer edge of an organic layer and has an opening through
 the adhesive that surrounds the multi-layer structure.
- 44. (previously presented): The article of claim 43 wherein the organic layers comprise a hole transporting layer, a light emitting layer, and an electron transporting layer.
- 45. (previously presented): The article of claim 40 further comprising a desiccant in the gap.
- 46. (previously presented): The article of claim 43 wherein the adhesive seals an outer edge of an anode or cathode.
- 47. (previously presented): The article of claim 43 wherein the adhesive seals all outer edges of an organic layer.
- 48. (previously presented): The article of claim 43 wherein the adhesive seals all outer edges of the multi-layer structure.
- 49. (previously presented): The article of claim 43 wherein the adhesive improves the device's structural stability.

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- 50. (previously presented): The article of claim 43 wherein the adhesive and multi-layer structure have approximately equal thicknesses.
- 51. (previously presented): The article of claim 43 wherein the adhesive thickness is greater than the multi-layer structure thickness.
- 52. (previously presented): The article of claim 43 wherein the adhesive is on the substrate and the sealing layer is on the adhesive.
- 53. (previously presented): The article of claim 43 wherein the multi-layer structure is encapsulated by the adhesive and sandwiched between the substrate and sealing layer.
- 54. (previously presented): An article comprising an organic electronic device which comprises:
 - a. a roll of flexible substrate;
 - b. an adhesive;
 - c. a release liner; and
 - d. a multi-layer structure comprising one or more organic layers
 between an anode and a cathode, the anode, cathode or an organic layer having at
 least one outer edge;

wherein the adhesive and release liner have a combined thickness greater than the multilayer structure thickness, and protect the multi-layer structure from damage in a roll to roll manufacturing process; and wherein the adhesive has an opening through it that surrounds the multi-layer structure.

55. (previously presented): The article of claim 54 wherein the adhesive seals an outer edge of an anode or cathode.

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- 56. (previously presented): The article of claim 54 wherein the adhesive seals an outer edge of an organic layer.
- 57. (previously presented): The article of claim 54 wherein the adhesive seals all outer edges of an organic layer.
- 58. (previously presented): The article of claim 54 wherein the adhesive seals all outer edges of the multi-layer structure.
- 59. (previously presented): The article of claim 54 wherein the adhesive and multi-layer structure have approximately equal thicknesses.
- 60. (previously presented): The article of claim 54 wherein the adhesive and release liner have complementary openings.
 - 61. (new): An organic electronic device precursor comprising:
 - a roll of flexible substrate comprising an electrode layer;
 - b. an adhesive;
 - c. a release liner; and
 - d. one or more organic layers on the electrode layer, the organic layer

or layers having at least one outer edge;
wherein the adhesive and release liner have a combined thickness greater than the
thickness of the organic layer or layers, and protect the organic layer or layers from
damage in a roll to roll manufacturing process; and wherein the adhesive has an opening
through it that surrounds the organic layer or layers.

62. (new): The precursor of claim 61 wherein the adhesive seals an outer edge of an electrode layer.

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- 63. (new): The precursor of claim 61 wherein the adhesive seals all outer edges of an organic layer.
- 64. (new): The precursor of claim 61 wherein the adhesive seals all outer edges of all organic layers.
- 65. (new): The precursor of claim 61 wherein the adhesive and the organic layer or layers have approximately equal thicknesses.
- 66. (new): The precursor of claim 61 wherein the adhesive and release liner have complementary openings.